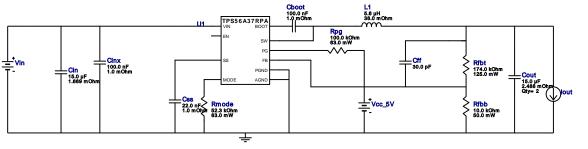


# WEBENCH<sup>®</sup> Design Report

VinMin = 12.0V VinMax = 22.0V Vout = 11.0V Iout = 4.0A Device = TPS56A37RPAR Topology = Buck Created = 2024-08-27 06:23:35.299 BOM Cost = \$2.88 BOM Count = 13 Total Pd = 1.69W

Design : 3188 TPS56A37RPAR TPS56A37RPAR 12V-22V to 11.00V @ 4A

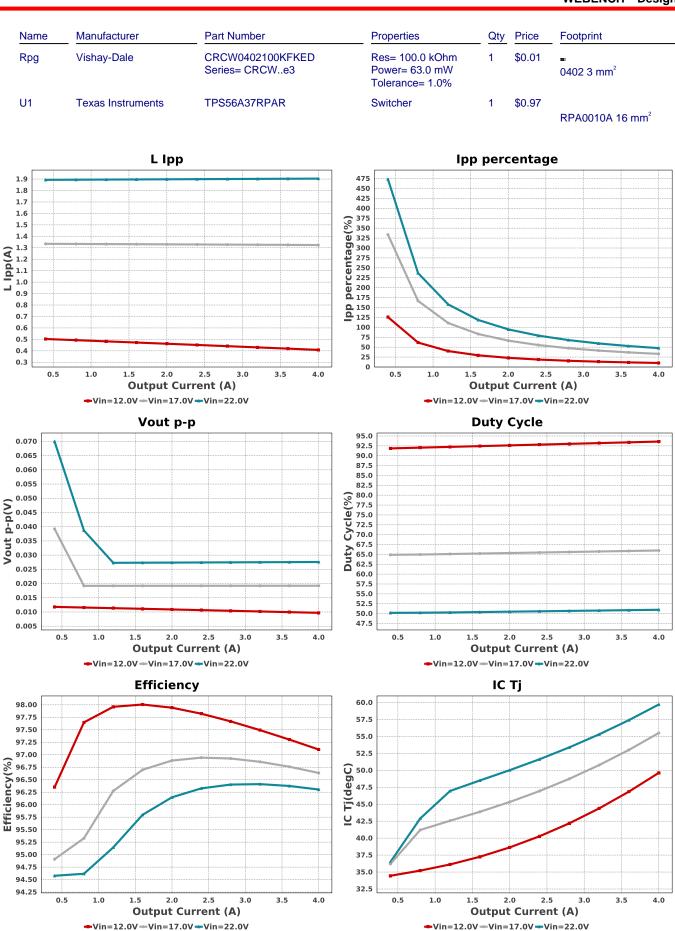


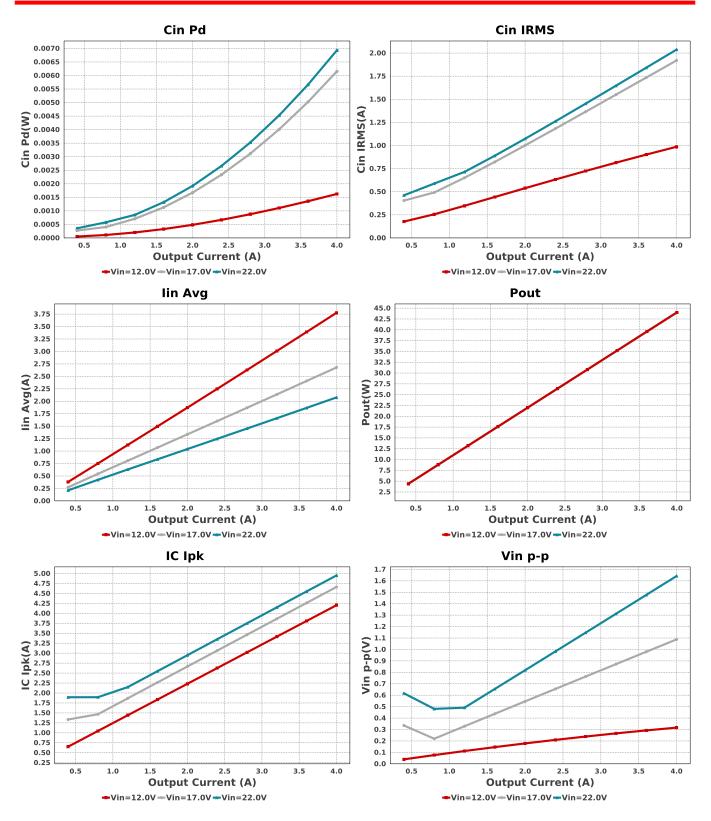
Vout = 11.0V

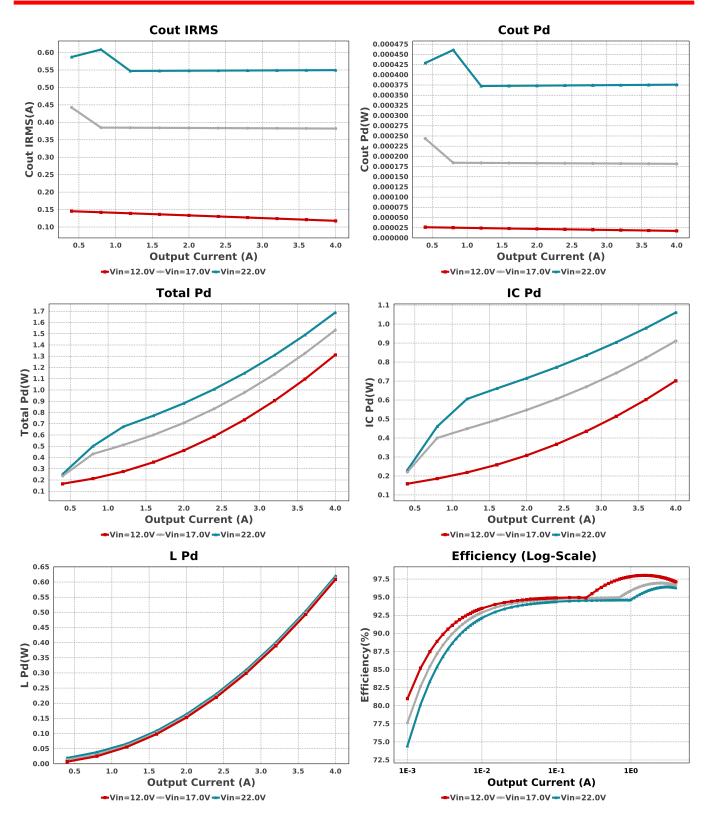
### **Electrical BOM**

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cboot	Taiyo Yuden	EMK107B7104KA-T Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	■ 0603 5 mm <sup>2</sup>
Cff	AVX	06033A300FAT2A Series= C0G/NP0	Cap= 30.0 pF VDC= 25.0 V IRMS= 0.0 A	1	\$0.10	■ 0603 5 mm <sup>2</sup>
Cin	ТDК	C2012X5R1V156M125AC Series= X5R	Cap= 15.0 uF ESR= 1.669 mOhm VDC= 35.0 V IRMS= 5.0498 A	1	\$0.20	0805 7 mm <sup>2</sup>
Cinx	Yageo	CC0805KRX7R9BB104 Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 50.0 V IRMS= 0.0 A	1	\$0.02	0805 7 mm <sup>2</sup>
Cout	ТDК	C4532X5R1E156M280KA Series= X5R	Cap= 15.0 uF ESR= 2.488 mOhm VDC= 25.0 V IRMS= 4.8625 A	2	\$0.41	1812_320 23 mm <sup>2</sup>
Css	MuRata	GRM155R71C223KA01D Series= X7R	Cap= 22.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	■ 0402 3 mm <sup>2</sup>
L1	Bourns	SRP6540-5R6M	L= 5.6 μΗ 38.0 mOhm	1	\$0.71	SRP6540 83 mm <sup>2</sup>
Rfbb	Yageo	RC0201FR-0710KL Series= ?	Res= 10.0 kOhm Power= 50.0 mW Tolerance= 1.0%	1	\$0.01	• 0201 2 mm <sup>2</sup>
Rfbt	Panasonic	ERJ-6ENF1743V Series= ERJ-6E	Res= 174.0 kOhm Power= 125.0 mW Tolerance= 1.0%	1	\$0.01	<b>0805 7 mm<sup>2</sup></b>
Rmode	Vishay-Dale	CRCW040252K3FKED Series= CRCWe3	Res= 52.3 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	••• 0402 3 mm <sup>2</sup>

#### WEBENCH<sup>®</sup> Design







### **Operating Values**

#	Name	Value	Category	Description
1.	Cin IRMS	2.038 A	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	6.93 mW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	549.619 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	375.79 µW	Capacitor	Output capacitor power dissipation
5.	IC lpk	4.952 A	IC	Peak switch current in IC
6.	IC Pd	1.061 W	IC	IC power dissipation
7.	IC Tj	59.712 degC	IC	IC junction temperature
8.	IC Tolerance	6.0 mV	IC	IC Feedback Tolerance
9.	ICThetaJA Effective	28.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
10.	lin Avg	2.077 A	IC	Average input current

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# WEBENCH<sup>®</sup> Design

#	Name	Value	Category	Description
11.	Ipp percentage	47.598 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
12.	L lpp	1.904 A	Inductor	Peak-to-peak inductor ripple current
	L Pd	619.48 mW	Inductor	Inductor power dissipation
14.	Cin Pd	6.93 mW	Power	Input capacitor power dissipation
15.	Cout Pd	375.79 μW	Power	Output capacitor power dissipation
16.	IC Pd	1.061 W	Power	IC power dissipation
17.	L Pd	619.48 mW	Power	Inductor power dissipation
18.	Total Pd	1.689 W	Power	Total Power Dissipation
19.	BOM Count	13	System	Total Design BOM count
10.	Dom ooun	10	Information	
20.	Duty Cycle	50.964 %	System	Duty cycle
_0.			Information	
21.	Efficiency	96.304 %	System	Steady state efficiency
	,		Information	
22.	FootPrint	186.0 mm <sup>2</sup>	System	Total Foot Print Area of BOM components
		100.0 11111	Information	·····
23.	Frequency	514.622 kHz	System	Switching frequency
			Information	
24.	lout	4.0 A	System	lout operating point
			Information	
25.	Mode	CCM	System	Conduction Mode
			Information	
26.	Pout	44.0 W	System	Total output power
			Information	
27.	Total BOM	\$2.88	System	Total BOM Cost
			Information	
28.	Vin	22.0 V	System	Vin operating point
			Information	
29.	Vin p-p	1.642 V	System	Peak-to-peak input voltage
			Information	
30.	Vout	11.0 V	System	Operational Output Voltage
			Information	
31.	Vout Actual	11.04 V	System	Vout Actual calculated based on selected voltage divider resistors
			Information	
32.	Vout Tolerance	2.93 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divider
			Information	resistors if applicable
33.	Vout p-p	27.578 mV	System	Peak-to-peak output ripple voltage
			Information	

# **Design Inputs**

Name	Value	Description	
lout	4.0	Maximum Output Current	
VinMax	22.0	Maximum input voltage	
VinMin	12.0	Minimum input voltage	
Vout	11.0	Output Voltage	
base_pn	TPS56A37	Base Product Number	
source	DC	Input Source Type	
Та	30.0	Ambient temperature	

# WEBENCH<sup>®</sup> Assembly

# Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

## Soldering Component to Board

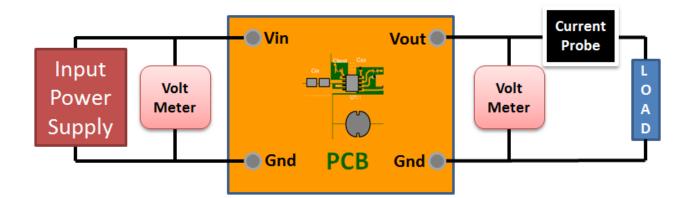
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

## Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 12.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

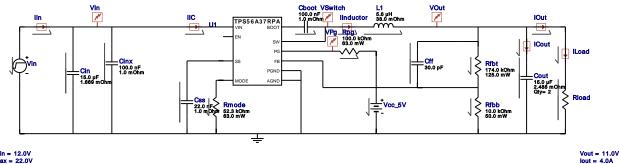
# Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



# WEBENCH<sup>®</sup> Electrical Simulation Report

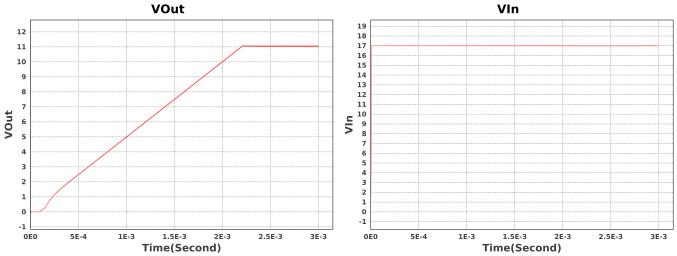
Design Id = 3188 sim\_id = 1 Simulation Type = Startup



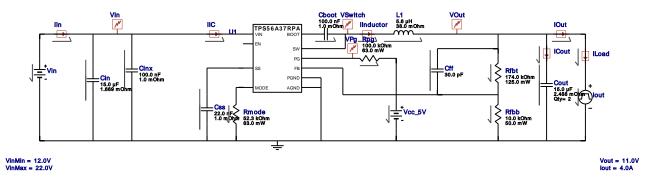
#### VinMin = 12.0V VinMax = 22.0V

#### **Simulation Parameters**



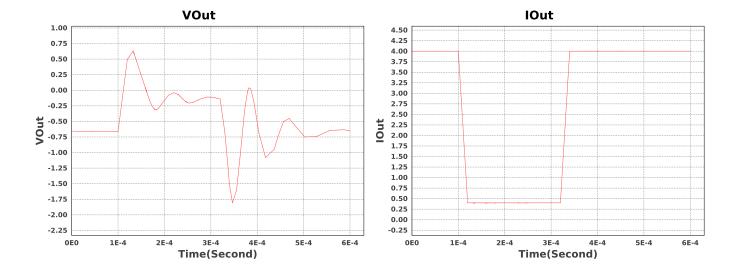


Design Id = 3188 sim\_id = 2 Simulation Type = Load Transient

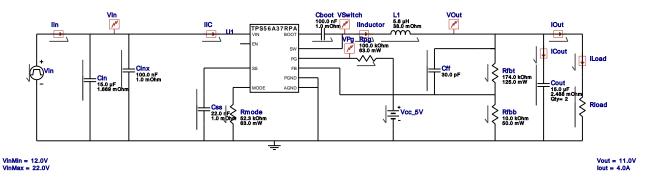


#### **Simulation Parameters**

#	Name	Parameter Name	Description	Values
1.	Cin	IC	intial voltage	17.0 V
2.	Cout	IC	initial voltage	11.0 V
3.	L1	IC	intial voltage	-4.0 A
4.	Cboot	IC	intial voltage	5 V
5.	Css	IC	intial voltage	5 V
6.	ILoad	1	Load Current	ILoad1 A
7.	lout	signal_type I1 I2 Td Tf Tr Pw	Signal Type Initial Load Current Minimum Load Current Initial Time Delay Fall Time Rise Time Pulse Width	PULSE 4.0 A 0.4 A 0.1m sec 20u sec 20u sec 0.2m sec



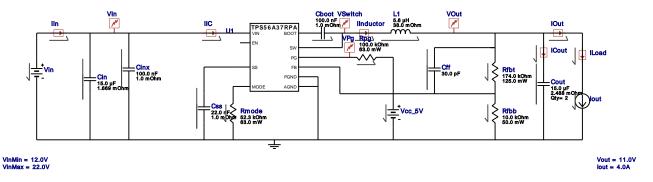
Design Id = 3188 sim\_id = 3 Simulation Type = Input Transient



#### **Simulation Parameters**

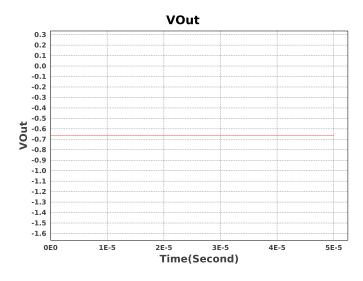
# Name	Parameter Name	Description	Values
1. Cout	IC	intial voltage	0 V
2. L1	IC	intial current	-4.0 A
3. Css	IC	intial voltage	5 V
4. Rload	R	Load Resistance	2.75 Ohm

Design Id = 3188 sim\_id = 4 Simulation Type = Steady State



#### **Simulation Parameters**

# Name	Parameter Name	Description	Values
1. Cin	IC	intial voltage	17.0 V
2. Cout	IC	intial voltage	11.0 V
3. L1	IC	Initial Current	-4.0 A
4. Cboot	IC	intial voltage	11.0 V
5. Css	IC	intial voltage	5 V
6. lout	I	Load Current	4.0



## **Design Assistance**

1. Master key : 4DBC92FC97185CFB[v1]

2. TPS56A37 Product Folder : http://www.ti.com/product/TPS56A37 : contains the data sheet and other resources.

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